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United States Patent [19]

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Adams

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[54] **METHOD OF SPIRAL RESIST DEPOSITION** 5,094,884 3/1992 Hillman 427/240

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[73] Assignee: **AT&T Corp.**, Murray Hill, N.J.

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[*] Notice: The term of this patent shall not extend beyond the expiration date of Pat. No. 5,395,803.

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[21] Appl. No.: **355,757**

Method For Coating Photoresist Patent Abstracts of Japan vol. 7, No. 70 (P-185) (1215) 23 Mar. 1983.

[22] Filed: **Dec. 14, 1994**

E-388 (2122) Patent Abstracts of Japan vol. 10, No. 65. 14 Mar. 1986.

Related U.S. Application Data

Patent No. Patent Abstracts of Japan, issued in Japan on 27 Jul. 1988 to Hiroki Nezu.

[63] Continuation of Ser. No. 118,538, Sep. 8, 1993, Pat. No. 5,395,803.

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[51] **Int. Cl.⁶** **H01L 21/312**

[57] ABSTRACT

[52] **U.S. Cl.** **437/229; 437/240; 118/52**

A method of depositing a material upon a substrate is disclosed. A material, such as photoresist, is deposited upon a substrate such as a semiconductor wafer by spinning the substrate and commencing deposition at the edge of the wafer and moving inward in a spiral pattern. The method produces a more uniform coating than hitherto available.

[58] **Field of Search** **437/229, 240; 118/52**

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7 Claims, 3 Drawing Sheets

